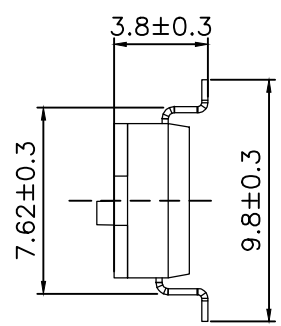
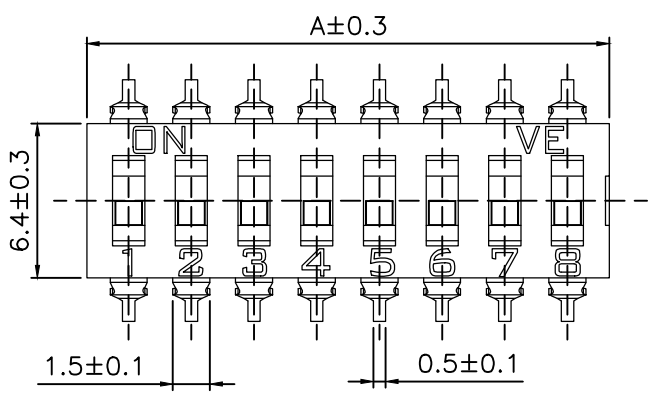
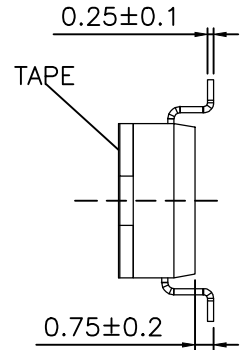


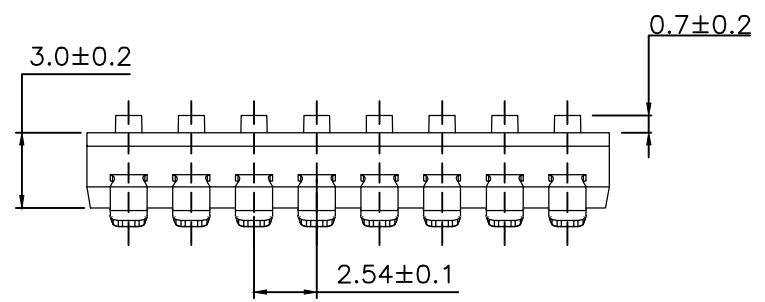
DIMENSION A											
POSITIONS	1	2	3	4	5	6	7	8	9	10	12
DIMA(MM)	2.7	5.95	8.50	11.0	13.55	16.1	18.63	21.2	23.7	26.25	31.3



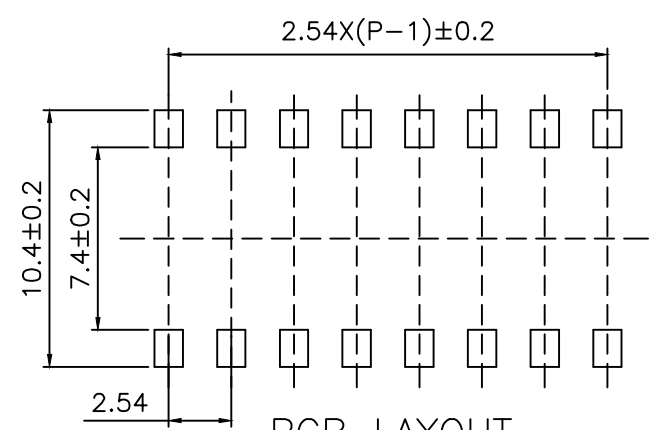
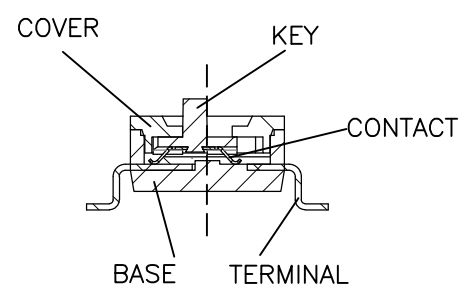
(H)HIGH KEY



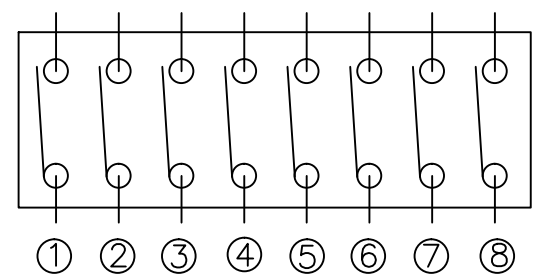
(L)LOW KEY



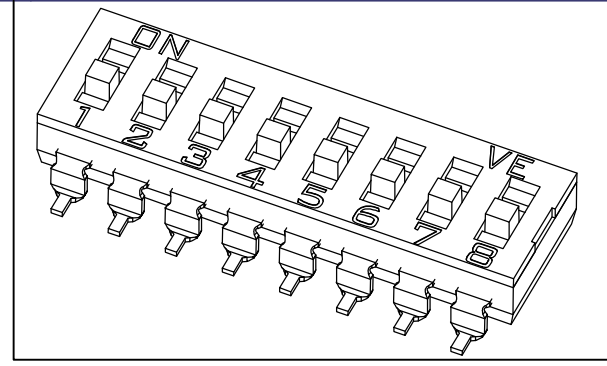
CONSTRUCTION



PCB LAYOUT



CIRCUIT DIAGRAM



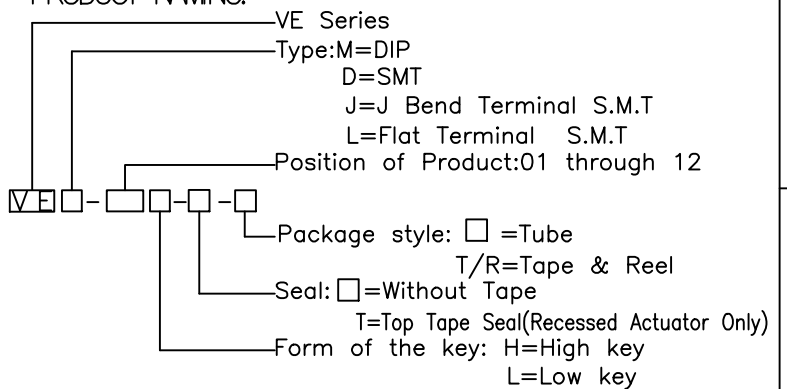
NOTES:
1.Materials

ITEM	DES	MATERIALS	TREATMENT
1	COVER	UL94 V0 grade Nylon Thermoplastic	BLACK
2	BASE	UL94 V0 grade Nylon Thermoplastic	BLACK
3	KEY	UL94 V0 grade Nylon Thermoplastic	WHITE
4	CONTACT	Alloy Coper	Plating Gold
5	TERMINAL	Brass	Plating Gold

2.Technical parameters

- 1>Operation force: 8N Max
- 2>Mechanical life: 3000 operations
- 3>Operating temperature: -25° to+70°
Storage temperature: -40° to+85°
- 4>Contact resistance(initial):≤50mΩ
Contact resistance(after life test):≤100mΩ
- 5>Resistance to soldering heat:
260±5° for 5±1seconds

PRODUCT NAMING:



DWG.BY:liuwei	DATE: 2014/04/08	TITLE	BY VE SERIES PITCH 2.54mm	Tolerance:	Units:mm
CHK.BY:	DATE:		TYPE HOUSING	X. ±0.3	Scale:free
APP.BY:	DATE:	PRAT NO	PRODUCT FAMILY VED SERIES	.X ±0.05	Sheet 1 of 1
		FILE NO.	VED-A	.XX ±0.02	A4
			REV. 1.0		